The quality assurance test of the SliT ASIC for the J-PARC muon *g* − 2/EDM experiment

Takashi Yamanaka^a, Yoichi Fujita^b, Eitaro Hamada^b, Tetsuichi Kishishita^b, Tsutomu Mibe^b, Yutaro Sato^c, Yoshiaki Seino^d, Masayoshi Shoji^b, Taikain Suehara^{e,f}, Manobu M. Tanaka^b, Junji Tojo^{e,f}, Keisuke Umebayashi^e, Tamaki Yoshioka^{e,f}

^aFaculty of Arts and Science, Kyushu University, 744 Motooka, Fukuoka, 819-0395, Japan

b Institute of Particle and Nuclear Studies, High Energy Accelerator Research Organization, 1-1 Oho, Tsukuba, 305-0801, Japan

^cDepartment of Physics, Faculty of Science, Niigata University, 8050 Ikarashi 2-no-cho, Niigata, 950-2181, Japan

^eDepartment of Physics, Faculty of Science, Kyushu University, 744 Motooka, Fukuoka, 819-0395, Japan

^fResearch Center for Advanced Particle Physics, Kyushu University, 744 Motooka, Fukuoka, 819-0395, Japan

Abstract

The SliT ASIC is a readout chip for the silicon strip detector to be used at the J-PARC muon *g*−2/EDM experiment. The production version of SliT128D was designed and mass production was finished. A quality assurance test method for bare SliT128D chips was developed to provide a sufficient number of chips for the experiment. The quality assurance test of the SliT128D chips was performed and 5735 chips were inspected. No defect was observed in chips of 84.3%. Accepting a few channels with poor time walk performance out of 128 channels per chip, more than 90% yield can be achieved, which is sufficient to construct the whole detector.

Keywords: quality assurance test, readout ASIC, probe card, silicon strip sensor

1. Introduction

A silicon strip detector will be used in the J-PARC muon *g*−2/EDM experiment to detect positrons from muon decay [\[1\]](#page-4-0). The detector is composed of 40 vane modules and each vane module has 16 silicon strip sensors. One sensor has 1024 strips and the total number of sensor strips in the whole detector modules is 655,360. To readout signals from silicon strip sensors, a new application specific integrated circuit (ASIC) named SliT was developed [\[2\]](#page-4-1). Performance evaluation was conducted at the pre-production version of SliT128C and it was confirmed to satisfy all requirements for the J-PARC muon *g*−2/EDM experiment. The mass-production version of SliT128D was designed with minor modifications to SliT1128C and its mass production was finished. One SliT128D chip has 128 readout channels so that 5120 chips are needed to readout all silicon strip sensor signals on the detector. To assure normal operation and performance of each chip before implementing it on a circuit board, a quality assurance system was developed and a large scale quality assurance test was conducted to provide sufficient number of chips for the detector. The test methods and results are described in this article.

2. Specifications and requirements of ASIC

2.1. Specifications

The SliT128D chip has a charge-sensitive amplifier (CSA) for the silicon strip sensor input. Test charge pulses can be also injected via an AC-coupling capacitor of 100 fF. The CSA output is fed into a CR-RC shaping amplifier whose peaking time is about 60 ns. A differentiator is implemented after the CR-RC

shaper. By using the zero-crossing timing of the differentiator output corresponding to the peak time of the CR-RC output, the time walk of signal can be reduced less than 1 ns which is required from the muon $g - 2$ /EDM experiment.

Bias voltages and currents for the shaping amplifiers and common thresholds for the comparators can be adjusted via pads on an ASIC chip. The comparator thresholds for the CR-RC shaper and differentiator can be adjusted further by 7-bit DACs independently for each channel by control registers.

The monitor lines are implemented to examine analog waveforms of the CSA, CR-RC shaper and differentiator. Waveforms of one channel selected by a control register can be monitored.

The signal timing is sampled by an external 200 MHz frequency clock. When the chip receives "write start" signal, it starts to store data in SRAMs with 8192 word depth for each channel.

A slow control circuit enables control of parameters for the analog and digital parts.

2.2. Requirements for the quality assurance test

Following functions and performance need to be tested as quality assurance.

- Power supply currents and bias voltages
- Slow control
- Analog waveforms
- Digital output of the CR-RC shaper and the differentiator
- Time walk of the differentiator output

^dNational Institute of Technology, Toyama College, 1-2 Ebie-neriya, Imizu, 933-0293, Japan

3. Test methods

3.1. Probe card

To test performance of the SliT128D chips, a probe card, which is a printed circuit board with probe needles, was designed and manufactured by Micronics Japan Ltd. The picture of the probe card is shown in Figure [1.](#page-1-0)

Figure 1: Probe card for the quality assurance test of SliT128D chips.

The probe card is a cantilever type and 110 probe needles made from tungsten-rhenium alloy are implemented. Probing positions can be viewed from the observing hole. Electric power for a SliT128D chip is supplied via a connector on the probe card to probe needles. The card also have analog waveform monitoring output connectors, and test pulse and write start input connectors. Variable resistances are implemented on the probe card for adjustment of bias voltages of a SliT128D chip. Measured bias voltages can be monitored from terminals on the probe card by connecting them to the external voltmeter.

The probe card has a FMC connector to install a Nexys Video board (manufactured by Digilent Inc.), which is a commercially available circuit board for FPGA development. Digital output is processed in an Artix-7 FPGA on the board.

3.2. Operation

The quality assurance test was performed with SliT128D chips after dicing. An operator set one chip on the chuck stage of the probe system and contacts probe needles of the probe card to the bonding pads of the chip. Electric power is supplied to the chip and measurements are performed one by one using the graphical user interface shown in Figure [2.](#page-1-1) After finishing the test of a chip, that chip is replaced by a new chip and the measurements are continued. A test of one chip typically takes 17 minutes including a few minutes of time for chip replacement.

3.3. Appearance inspection

Appearance of the chip is inspected by the macroscopy as well as the microscope. A chip with any dust or scratch is regarded as a defective chip. It is noted that the most of chips with appearance defects were removed in the mass production process.

		\Box \times SliT128D QA GUI
Ų Takashi Yamanaka Operator	反 Save	End
Set value Current value		
$5 -$ 5 Batch No.	反 Set	Appearance defects П Save
$6\frac{2}{7}$ 6 Tray No.		$\overline{\vee}$ S-curve scan Run
$20 -$ Chip No. 20		\Box NG comment Save
$1\frac{4}{7}$ $\mathbf{1}$ Meas, No.		CRRC: Noise 0.05307 Gain 13.58 Offset 31.87
Prober height 10.0×10 um	$\overline{\nabla}$ Save	$N(noisy)$ 0 N(dead) $\mathbf 0$
+1.8VD current at probing 195 mA	$\overline{\vee}$ Save	DIFF: Noise 1.26 Offset 60.38
Success Result Slow control	反 Run	$N(noisy)$ 0 $N(dead)$ 0
$0 -$ Analog monitor Ch Reset	$\overline{\vee}$ Set	Timewalk measurement $\overline{\vee}$ Run
NG comment	厂 Save	\Box NG comment Save
Power supply/bias measurement	$\overline{\vee}$ Run	$N(>1$ ns) $N(fail)$ 0 Average 0.287 ns $\mathbf{0}$
NG comment	厂 Save	Threshold scan
Timewalk measurement is finished.		

Figure 2: Graphical user interface for the quality assurance test.

3.4. Slow control test

Slow control function of the chip is tested by sending read and write signal to a control register. If slow control fails, there is no response from the chip.

3.5. Analog waveform monitor

Analog waveforms of the fixed channel are obtained by an oscilloscope and are checked whether they are nominal waveforms or not. Single triggered waveforms and the average waveforms are taken as shown in Figure [3.](#page-1-2)

Figure 3: Example of analog waveform monitoring. The CSA (top right), the CR-RC (bottom left) and the differentiator (bottom right) waveforms are shown with the test pulse timing signal (top left).

3.6. Power supply currents and bias voltages

Power supply currents are readout from a DC power supply. Bias voltages are monitored via connectors on the probe card and readout by a multimeter. These parameters are measured in four different conditions (whether readout clock and sampling clock are on or off) and are compared with pre-measured reference values as shown in Figure [4.](#page-2-0) If measured values significantly deviate from the reference values, that chip is regarded as defective.

Decrease of the power supply currents and bias voltages also occur when ASIC pad shavings pile-up on the probe needles.

Figure 4: Example of power supply currents and bias voltage measurement

When significant decrease is observed, cleaning of probe needles is performed using a wrapping film sheet and polyurethane cleaning sheet.

3.7. Threshold scan

Performance of the CR-RC shaper is evaluated by injecting test charge pulses and counting the detection efficiency as a function of the comparator threshold. Three different charges are injected and noise, gain and baseline voltage are measured for each channel. Example of the threshold scan for the CR-RC shaper is shown in Figure [5.](#page-2-1) For the differentiator circuit, the baseline voltage is measured by the threshold scan without injecting a test charge.

Figure 5: Example of the threshold scan for the CR-RC shaper. Upper eight plots show the detection efficiency of test pulses as a function of the comparator threshold. Lower eight plots show the center value of the detector efficiency as a function of input charges.

After these measurements, the threshold of the CR-RC shaper is set to the nominal value of 0.3 minimum ionizing particle (MIP) charge and the threshold for the differentiator circuit is set to the baseline voltage. Short data is taken with or without a test charge injection. Noisy channel shows non-existence hit even without a test charge injection.

3.8. Time walk measurement

The time walk performance of the differentiator circuit is evaluated by injecting test charges of 0.5 MIP, 1 MIP and 3 MIP to each channel. The largest signal timing difference between them is defined as the time walk in the quality assurance test.

The best (smallest) time walk value is obtained when scanning the threshold for the differentiator circuit for each channel but it takes too long time for the quality assurance test. The test with about 600 chips showed that channels with time walk less than 2 ns with a fixed threshold near the average of the best thresholds satisfy the requirement of 1 ns time walk at the best threshold. Following this fact, the quality assurance test in a large volume was performed with the fixed threshold for time walk measurement. If the time walk is less than 2 ns, this channel is regarded to satisfy the requirement. One chip is sampled out of twenty chips and the threshold scan is performed for time walk measurement to confirm this estimate.

4. Results

4.1. Summary of defects

The test was performed at Kyushu University installing the probe card on a manual probe system (PM8 manufactured by FormFactor Inc.). The total number of measured chips was 5735.

Each chip is categorized by the severity of found defects in the following order.

- 1. Appearance defects
- 2. Abnormal power supply current
- 3. Slow control failure
- 4. Include at least one defective channels
- 5. Include at least one channel with time walk higher than the requirement
- 6. Abnormal analog waveforms

If none of the above defects are found, that chip is regarded as a no defective chip. The test result is summarized in Table [1.](#page-2-2)

Table 1: The result of the quality assurance test of SliT128D chips. Defects are ordered by the severity.

Defect	Number
Appearance defects	3
Abnormal power supply current	23
Slow control failure	
Defective channels	291
High time walk channels	560
Abnormal analog waveforms	21
No defect	4833
Total	5735

4.2. Appearance defects

Only three chips were regarded as an appearance defective chip. They are due to dusts on a chip which are expected to be attached in manufacturing process, or scratch due to an operation failure in the quality assurance test.

4.3. Defective channels

A channel with no digital output, having non-existence hits or showing any other malfunction (e.g. signal inefficiency even in the lowest comparator threshold, overcounting of signal hits due to ringing waveforms) is regarded as a defective channel. The number of defective channels in one chip after removing chips with severer defects is shown in Figure [6.](#page-3-0) The ratio of chips with at least one defective channels is 5.07% of the total inspected chips but the most of those chips having only a few defective channels.

Figure 6: The number of defective channels per chip after removing severer defects.

4.4. Time walk measurement

The number of channels per chip whose time walk value exceeds the requirement after removing chips with severer defects is shown in Figure [7.](#page-3-1) This number distributes up to a lager number continuously, though the most of chips have only a few channels with high time walk. Although channels to be used for hit time measurement need to satisfy the time walk requirement, it is not necessary that all channels in one chip satisfy the requirement. Thus, chips with small number of channels with high time walk can be used in practice.

Figure 7: The number of channels per chip whose time walk value exceeds the requirement after removing severer defective chips.

4.5. Abnormal analog waveforms

Abnormal analog waveforms are observed in chips with a certain defect but also in chips without any defects sometimes. Even though abnormal analog waveform itself does not affect practical usage if digital output is fine, those chips are also regarded as defective chips for safety.

4.6. Yield

The ratio of no defective chips is 84.3%. To provide a sufficient number of chips for the experiment (i.e. 5120 chips), more than 89.3% yield is needed. This yield can be obtained by accepting a few channels with high time walk in one chip. The yield as a function of the number of accepted channels with high time walk is shown in Figure [8.](#page-3-2) To secure 5120 chips, at least three channels with high time walk need to be accepted.

Figure 8: The ratio of defective chips as a function of the number of accepted channels with high time walk. A dotted line indicates the target yield of 89.3%.

5. Conclusion

The quality assurance test of SliT128D chips was performed to confirm their normal operation and performance before assembling into the detector module for the muon *g* − 2/EDM experiment at J-PARC. The test of 5735 chips were performed and 84.3% chips were found to have no defects. The most of defects are the existence of at least one defective channels or channels with high time walk than the requirement. Accepting at least three channels with high time walk in one chip, a sufficient number of chips for the whole detector can be provided.

Acknowledgments

This research was supported by JSPS KAKENHI Grants No. JP20H05625 and 22H01232. The authors would like to acknowledge the Open Source Consortium of Instrumentation (Open-It) of KEK for their support on the electronics design.

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